

ON Semiconductor®

FDMS5361L-F085

N-Channel PowerTrench[®] MOSFET 60 V, 35 A, 15 m Ω

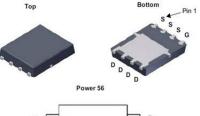
Features

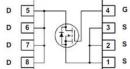
- Typ r_{DS(on)} = 11.7 mΩ at V_{GS} = 10 V, I_D = 16.5 A
- Typ Q_{g(tot)} = 37 nC at V_{GS} = 10 V, I_D = 16.5 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems







For current package drawing, please refer to the our website at www.onsemi.com

MOSFET Maximum Ratings $T_J = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain to Source Voltage		60	V	
V _{GS}	Gate to Source Voltage		±20	V	
I _D	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C =25°C	35	^	
	Pulsed Drain Current	T _C = 25°C	See Figure4	Α	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	82	mJ	
	Power Dissipation		75	W	
PD	Derate above 25°C		0.5	W/ºC	
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.0	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	50	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS5361L	FDMS5361L-F085	Power 56	13"	12mm	3000 units

Notes:

2: Starting $T_J = 25^{\circ}$ C, L = 0.21mH, $I_{AS} = 28$ A, $V_{DD} = 60$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche.

3: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

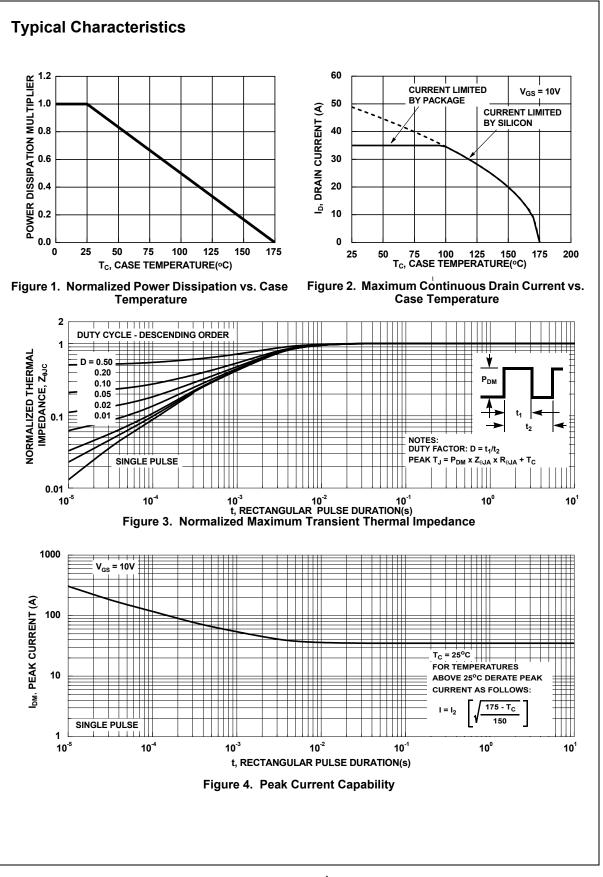
^{1:} Current is limited by junction temperature.

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
Off Cha	racteristics						
B _{VDSS}	Drain to Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V		60	-	-	V
	Drain to Source Leakage Current	V _{DS} =60V,	T _J = 25 ^o C	-	-	1	μA
I _{DSS}		$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA
On Cha	racteristics						
V _{GS(th)}	Gate to Source Threshold Voltage	V_{GS} = V_{DS} , I_D	= 250µA	1.0	1.84	3.0	V
		I _D = 16.5A,	T _J = 25 ^o C	-	11.7	15	mΩ
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 10V	$T_{J} = 175^{\circ}C(Note 4)$	-	24.5	30	mΩ
		I _D = 16.5A,	T _J = 25 ^o C	-	14.6	18	mΩ
			$T_J = 175^{\circ}C(Note 4)$	-	29.5	34	mΩ
C _{iss} C _{oss}	Input Capacitance Output Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz		-	1980 176	-	pF pF
C _{oss}	Output Capacitance			-		-	•
C _{rss}	Reverse Transfer Capacitance	C 4141			93	-	pF
R _g	Gate Resistance	f = 1MHz	1	-	1.6	-	Ω
Q _{g(ToT)}	Total Gate Charge at 10V		$V_{GS} = 0 \text{ to } 10V$ $V_{DD} = 30V$		37	44	nC
Q _{g(th)}	Threshold Gate Charge	V_{GS} = 0 to 2V	I _D = 16.5A	-	3.6	5	nC
Q _{gs}	Gate to Source Gate Charge		_	-	5.5 7.3	-	nC
	Gate to Drain "Miller" Charge			-	1.3	-	nC
Q _{gd}							
	ng Characteristics						
Switchi	ng Characteristics			-	-	30	ns
Switchi			-	-	- 16	30 -	ns ns
Switchi t _{on} t _{d(on)}	Turn-On Time	V _{DD} = 30V, I _C	, = 16.5A,			30 - -	-
Switchi t _{on} t _{d(on)} t _r	Turn-On Time Turn-On Delay	V _{DD} = 30V, I _D V _{GS} = 10V, R	o = 16.5A, _{GEN} = 6Ω	-	16	30 - - -	ns
	Turn-On Time Turn-On Delay Rise Time	V _{DD} = 30V, I _C V _{GS} = 10V, R	o = 16.5A, _{GEN} = 6Ω	-	16 10	30 - - - -	ns ns

V_{SD}	Source to Drain Diode Voltage	I _{SD} = 16.5A, V _{GS} = 0V	-	-	1.25	V
t _{rr}	Reverse Recovery Time	$I_{F} = 16.5A, dI_{SD}/dt = 100A/\mu s,$	-	28	32	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} =48V	-	25	33	nC

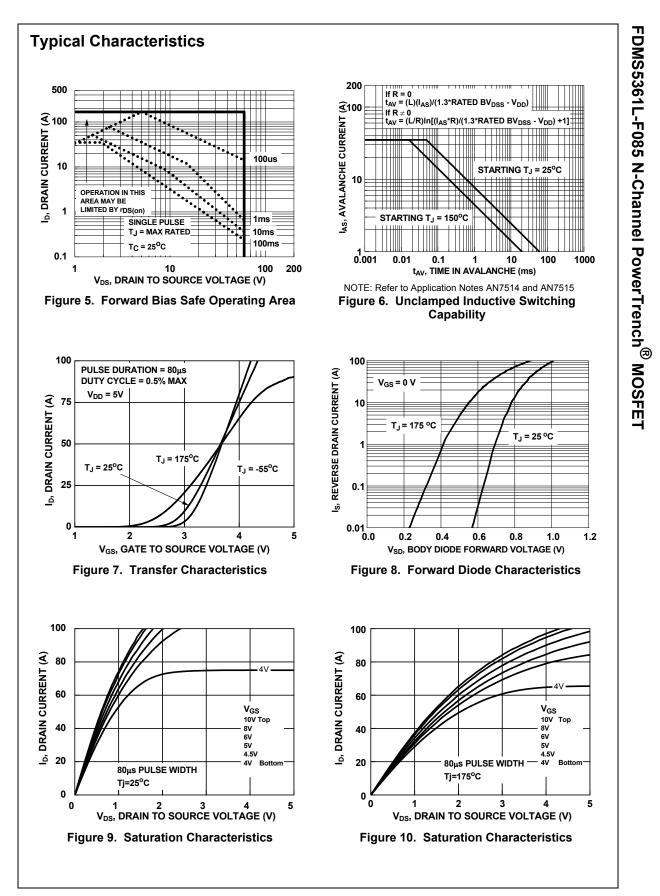
Note:

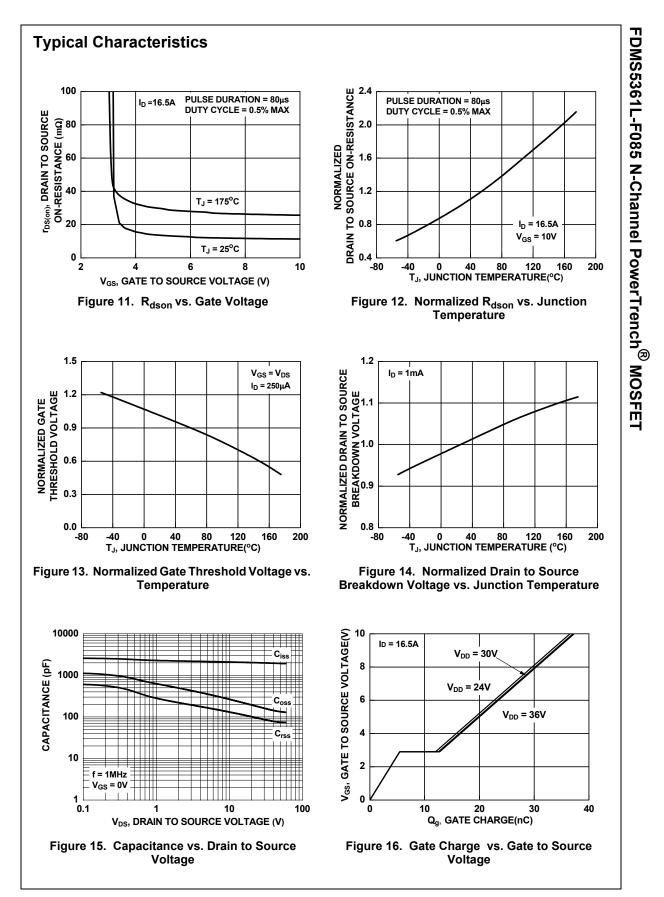
4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.



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